

# 应用于高端线路板之下一代垂直化铜工艺 (离子钯系统)

## Next Generation Vertical Electroless Copper Process with Ionic Pd Catalyst System for High-end products

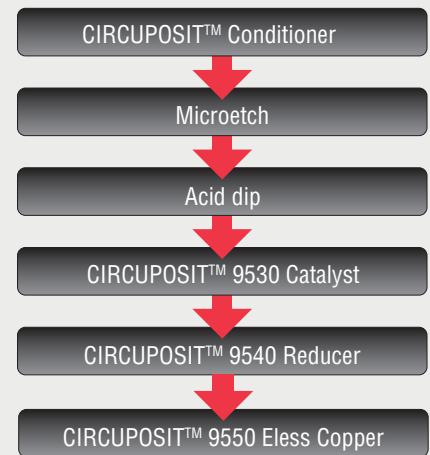


### CIRCUPOSIT™ 9500 Vertical Electroless Copper Process

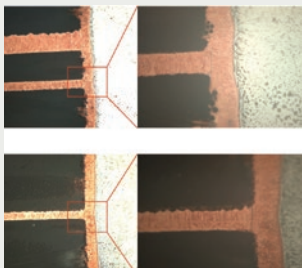
#### Features and Benefits 特长及优点

- Excellent quality in micro-via and through hole  
具有优良盲孔及通孔的品质表现
- Good coverage on different materials.  
绝佳的镀层复盖能力，能处理多种不同板材。
- Excellent reliability performance: ICD free and pass all reliability testing  
绝佳的品质信赖性表现，没有ICD问题，并通过所有的信赖性测试
- Fine grain structure of electro-less copper and good adhesion on inter-connections.  
极细致的化学铜结构，在铜层交界面有良好之结合力。
- High catalyst and electroless copper bath stability, helping to lower the operation cost of ownership  
活化及化学铜槽液有良好的稳定性，有助降低使用者的操作成本
- Applied to high-end mobile device (Smartphone), automotive, telecom and server products with blind via design and high aspect through holes  
适用于各类高端手机、汽车板、通讯板、伺服器等含有盲孔及高纵横比通孔的设计。

#### Process: 制程



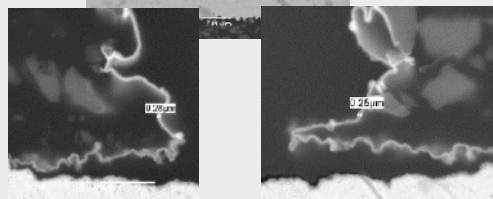
Solder float test: 288 °C,  
10 sec @10 cycles



FR408HR

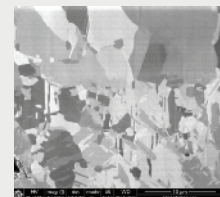
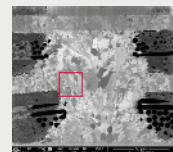
FR370HR

FR4 material, Tg = 170 °C

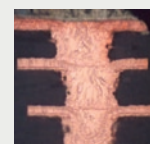


Good Eless Cu throwing power on microvia

Stack via process



No micro cracking on microvias after thermal stress



Stacked microvias  
叠加盲孔